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PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.
MI22-1363SERIAL NO.
09/512,968LIST OF ART CITED BY APPLICANT
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U.S. PATENT DOCUMENTS

*Examiner Initial		Document Number	Date	Name	Class	Subclas s	Filing Date If Appropriate
	AA	5,612,574	3/18/97	Summerfelt et al.			
	AB	5,719,333	2/17/98	Hosoi et al.			
	AC	5,831,333	11/3/98	Malladi et al.			
	AD	5,919,548	7/6/99	Barron et al.			
	AE	5,551,283	9/3/96	Manaka et al.			
	AF	5,492,011	2/20/96	Amano et al.			
	AG						
	AH						
	AJ						

FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Subclas s	Translation	
							Yes	No
3	AK							
3	AL							
4	AM							
6	AO							

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)

2	AP		"NTC and PTC Thermistors"; http://www.thermodisc.com/ntcptc.html ; 1/7/98; 2 pages.					
5	AR		"DI-5B35 Linearized 4-Wire RTD Input"; http://www.dataq.com/di5b35.html ; 1/7/98; 2 pages.					
E	AS		"RTD"; http://www.mtisensors.com/rtds.html ; 1/7/98; 3 pages.					
0	AT		"Low Cost Thermal-Ribbon (TM) uses thin film RTD"; http://www.minco.com/s17624nr.html ; 1/7/98; 1 page.					
5	AU		"Silicon Processing for the VLSI Era"; Volume 1 - Process Technology, Second Edition; S. Wolf et al.; 2000; pps 22-25 and pps. 841-845.					

EXAMINER

DATE CONSIDERED

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.